

## LTM4631 G311E Qualification Results Summary

Test Name	Specification	Conditions	Sample Size (lot x samples)	Result
Solder Heat Resistance (SHR) *	J-STD-020	MSL-3	1 X 77	Pass
Thermal Shock (TS) *	JESD22-A106	-55°C/+125°C, 1,000 Cycles	1 X 77	Pass

\*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 245°C.

## LTM4631 BGA at ASEK Qualification Results Summary

Test Name	Specification	Conditions	Device	Sample Size (lot X samples)	Result
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	LTM4631	1 x 50	Pass
Solder Heat Resistance (SHR) <sup>1</sup>	J-STD-020	MSL-Other	LTM4631	1 x 50	Pass
Temperature Cycling (TC) <sup>2</sup>	JESD22-A104	-55°C/+125°C, 1,000 Cycles	LTM4631	1 x 77	Pass
Thermal Shock (TS) <sup>2</sup>	JESD22-A106	-55°C/+125°C, 1,000 Cycles	LTM4631	1 x 77	Pass
Unbiased HAST (UHST) <sup>2</sup>	JESD22-A118	110C 85%RH 17.7 psia, P264	LTM4631	1 x 77	Pass

<sup>1</sup> These samples were subjected to preconditioning (per J-STD-020 Level Other) prior to the start of the stress test.

Level Other preconditioning consists of the following: Bake: 48 hrs @ 125°C, Unbiased Soak: 8 hrs @ 30°C, 60%RH, Reflow: 1 pass through an oven with a peak temperature of 260°C.

<sup>2</sup> These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 48 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 250°C.